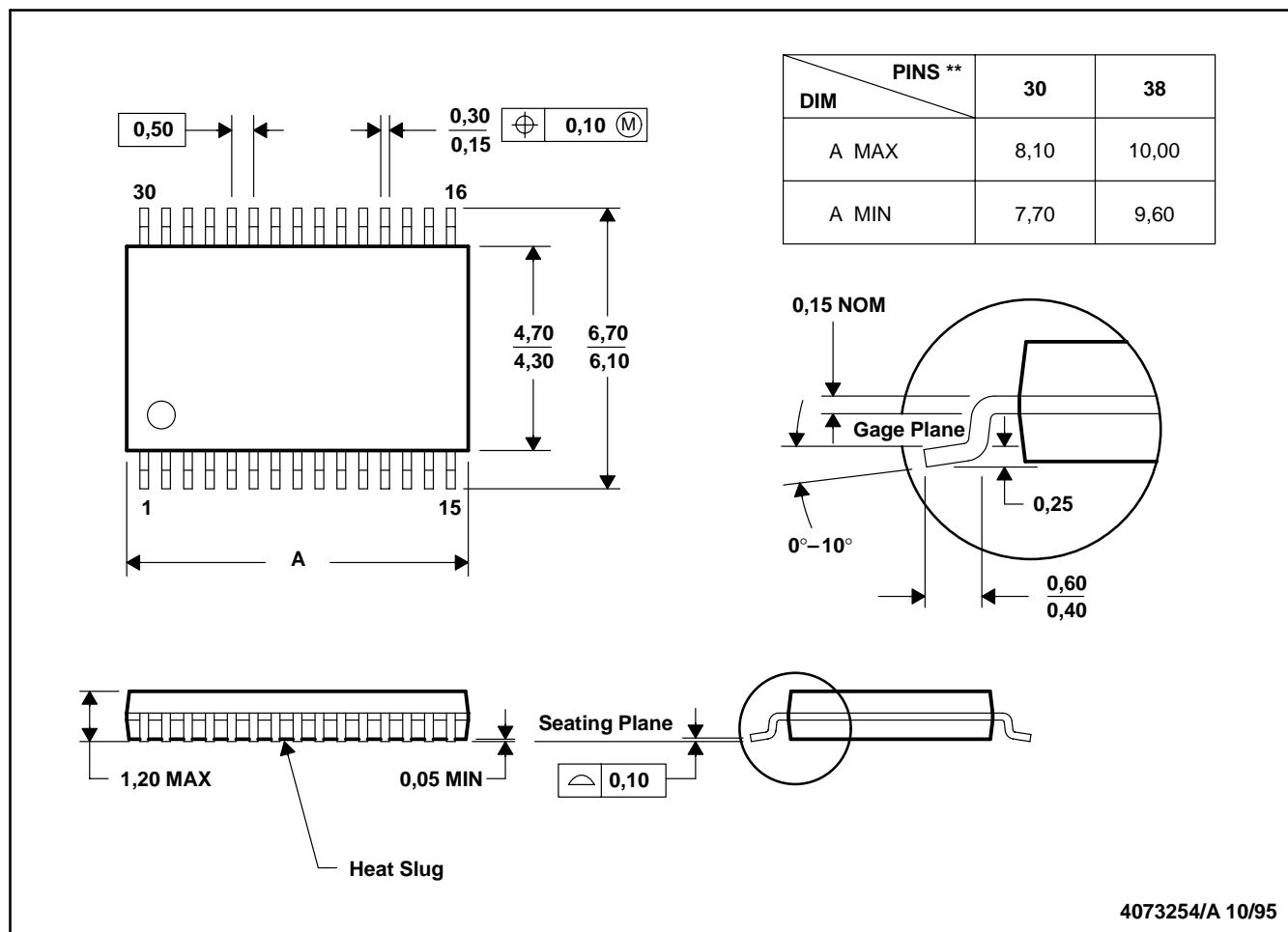


DBU (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

30 PIN SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions include mold flash or protrusion.
 D. Thermally enhanced molded plastic package with a exposed heat slug (HSL) on bottom

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